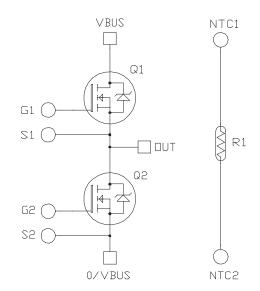
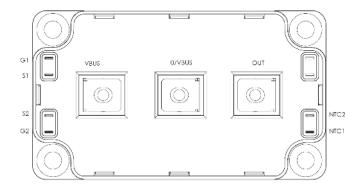


## Phase Leg SiC MOSFET Power Module

#### **Product Overview**

The MSCSM120AM027T6AG device is a full bridge 1200V, 733A phase leg silicon carbide (SiC) MOSFET power module.





**Note:** All ratings at  $T_J = 25$  °C, unless otherwise specified.

A CAUTION These devices are sensitive to electrostatic discharge. Proper handling procedures must be followed.

### Features

The following are the key features of the MSCSM120AM027T6AG device:

- SiC Power MOSFET
  - Low R<sub>DS(on)</sub>
  - High temperature performance
- Kelvin source for easy drive
- Low stray inductance
- M5 power connectors
- Internal thermistor for temperature monitoring
- Aluminum Nitride (AIN) substrate for improved thermal performance

### **Benefits**

The following are the benefits of MSCSM120AM027T6AG device:

- High efficiency converter
- Outstanding performance at high frequency operation
- Stable temperature behavior
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- RoHS compliant

## Application

The MSCSM120AM027T6AG device is designed for the following applications:

- Welding converters
- Switched mode power supplies
- Uninterruptible power supplies
- EV motor and traction drive

#### 1. Electrical Specifications

This section provides the electrical specifications of the MSCSM120AM027T6AG device.

#### 1.1 SiC MOSFET Characteristics (Per SiC MOSFET)

The following table lists the absolute maximum ratings per SiC MOSFET of the MSCSM120AM027T6AG device.

#### Symbol Parameter **Maximum Ratings** Unit V<sub>DSS</sub> Drain-Source voltage 1200 V Continuous drain current T<sub>C</sub> = 25 °C 733<sup>1</sup> А $I_D$ T<sub>C</sub> = 80 °C 584<sup>1</sup> Pulsed drain current 1400 I<sub>DM</sub> -10/23 V $V_{GS}$ Gate-Source voltage R<sub>DS(on)</sub> Drain-Source ON resistance 3.5 mΩ T<sub>C</sub> = 25 °C 2970 W $P_D$ Power dissipation

#### Table 1-1. Absolute Maximum Ratings

#### Note:

1. SiC MOSFET device specification, but the output current must be limited due to the size of the power connectors.

The following table lists the electrical characteristics per SiC MOSFET of the MSCSM120AM027T6AG device.

Table 1-2. Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min.	Тур.	Max.	Unit
I <sub>DSS</sub>	Zero gate voltage drain current	V <sub>GS</sub> = 0V V <sub>DS</sub> = 1200V		—	90	900	μA
R <sub>DS(on)</sub>	Drain–Source on	V <sub>GS</sub> = 20V	T <sub>J</sub> = 25 °C	—	2.8	3.5	mΩ
	resistance	I <sub>D</sub> = 360A	T <sub>J</sub> = 175 °C	_	4.45	_	
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{GS} = V_{DS}$ I <sub>D</sub> = 27 mA		1.8	2.8	—	V
I <sub>GSS</sub>	Gate–Source leakage current	V <sub>GS</sub> = 20V; V <sub>DS</sub> = 0	V	_	_	900	nA

#### **Electrical Specifications**

The following table lists the dynamic characteristics per SiC MOSFET of the MSCSM120AM027T6AG device.

Symbol	Characteristic	Test Conditions		Min.	Тур.	Max.	Unit
C <sub>iss</sub>	Input capacitance	V <sub>GS</sub> = 0V		—	27	_	nF
C <sub>oss</sub>	Output capacitance	V <sub>DS</sub> = 1000V		_	2.43	_	
C <sub>rss</sub>	Reverse transfer capacitance	f = 1 MHz			0.23		
Qg	Total gate charge	$V_{GS} = -5V/20V$		_	2088		nC
Q <sub>gs</sub>	Gate-Source charge	V <sub>Bus</sub> = 800V		_	369		
Q <sub>gd</sub>	Gate-Drain charge	I <sub>D</sub> = 360A		_	450	_	
T <sub>d(on)</sub>	Turn-on delay time	V <sub>GS</sub> = -5V/20V	T <sub>J</sub> = 150°C	_	74		ns
Tr	Rise time	V <sub>Bus</sub> = 600V		_	96		
T <sub>d(off)</sub>	Turn-off delay time	I <sub>D</sub> = 450A		_	150		
T <sub>f</sub>	Fall time	$R_{G(on)} = 4.7\Omega$ $R_{G(off)} = 1.8\Omega$			51		
Eon	Turn-on energy	V <sub>GS</sub> = -5V/20V	T <sub>J</sub> = 150 °C	_	16		mJ
E <sub>off</sub>	Turn-off energy	$V_{Bus}$ = 600V $I_D$ = 450A $R_{G(on)}$ = 4.7 $\Omega$ $R_{G(off)}$ = 1.8 $\Omega$	T <sub>J</sub> = 150 °C	_	9.2		
R <sub>Gint</sub>	Internal gate resistance	Internal gate resistance		_	0.65	_	Ω
R <sub>thJC</sub>	Junction-to-case thermal res	istance			_	0.051	°C/W

#### Table 1-3. Dynamic Characteristics

The following table lists the body diode ratings and characteristics per SiC MOSFET of the MSCSM120AM027T6AG device.

Table 1-4. Body Diode Ratings and Characteristics

Symbol	Characteristic	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>SD</sub>	Diode forward voltage	V <sub>GS</sub> = 0V; I <sub>SD</sub> = 360A	—	4	_	V
		$V_{GS} = -5V; I_{SD} = 360A$	—	4.2		
t <sub>rr</sub>	Reverse recovery time	I <sub>SD</sub> = 360A; V <sub>GS</sub> = –5V		90		ns
Q <sub>rr</sub>	Reverse recovery charge	V <sub>R</sub> = 600V; di <sub>F</sub> /dt = 9000 A/µs		4950		nC
Irr	Reverse recovery current			122	_	А

#### **Electrical Specifications**

#### 1.2 Thermal and Package Characteristics

The following table lists the thermal and package characteristics of the MSCSM120AM027T6AG device.

Symbol	Characteristics			Min	Max	Unit
V <sub>ISOL</sub>	RMS isolation voltage, any termin	nal to case t =1 min,	50 Hz/60 Hz	4000	—	V
TJ	Operating junction temperature ra	ange		-40	175	°C
T <sub>JOP</sub>	Recommended junction temperat	ure under switching	conditions	-40	T <sub>Jmax</sub> –25	
T <sub>STG</sub>	Storage temperature range			-40	125	
T <sub>C</sub>	Operating case temperature	Operating case temperature		-40	125	
Torque	Mounting torque	For terminals	M5	2	3.5	N.m
		To heatsink	M6	3	5	
Wt	Package weight			_	300	g

#### Table 1-5. Thermal and Package Characteristics

The following table lists the temperature sensor NTC of the MSCSM120AM027T6AG device.

#### Table 1-6. Temperature Sensor NTC

Symbol	Characteristic		Min	Тур	Max	Unit
R <sub>25</sub>	Resistance at 25°C		_	50	—	kΩ
$\Delta R_{25}/R_{25}$	—	—		5	_	%
B <sub>25/85</sub>	T <sub>25</sub> = 298.15 K	—		3952	_	К
ΔΒ/Β	—	T <sub>C</sub> = 100 °C		4		%

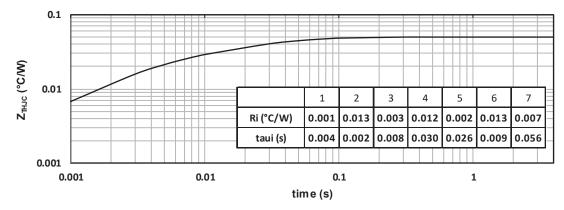
$$R_{T} = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$
 T: Thermistor temperature  
R<sub>T</sub>: Thermistor value at T

Note: See APT0406—Using NTC Temperature Sensor Integrated into Power Module for more information.

#### **Electrical Specifications**

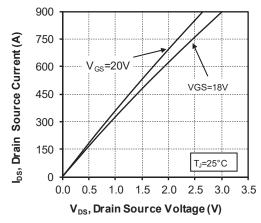
#### 1.3 Typical SiC MOSFET Performance Curve

This section shows the typical SiC MOSFET performance curves of the MSCSM120AM027T6AG device.

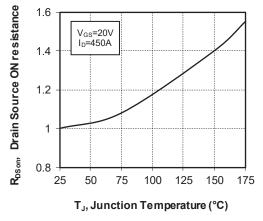


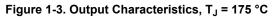
#### Figure 1-1. Maximum Thermal Impedance











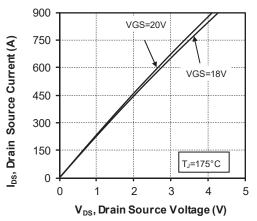
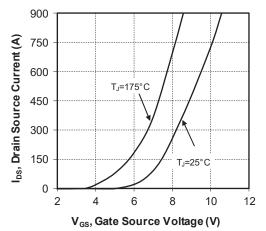
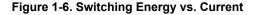
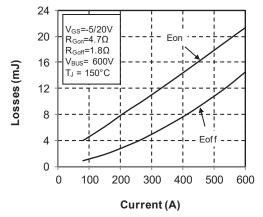


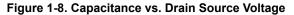
Figure 1-5. Transfer Characteristics

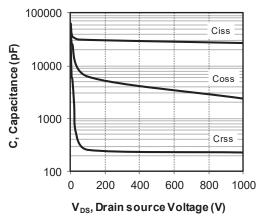


**Electrical Specifications** 











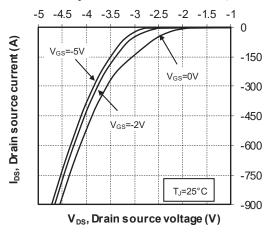


Figure 1-7. Switching Energy vs. Rg

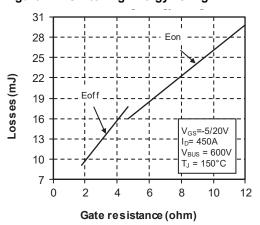


Figure 1-9. Gate Charge vs. Gate Source Voltage

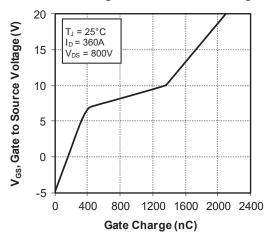
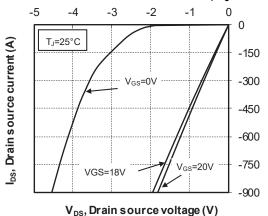
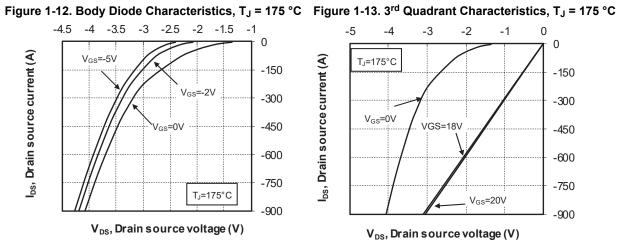


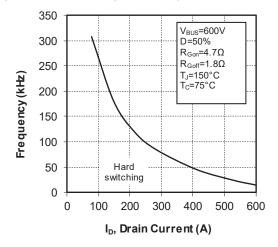
Figure 1-11. 3<sup>rd</sup> Quadrant Characteristics, T<sub>J</sub> = 25 °C



**Electrical Specifications** 







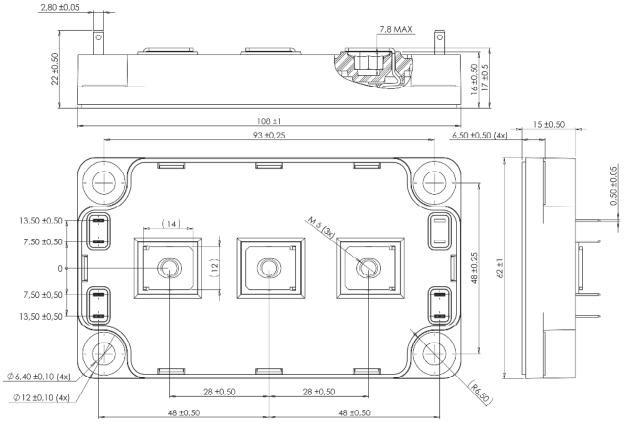
#### 2. Package Specifications

The following section shows the package specification of the MSCSM120AM027T6AG device.

#### 2.1 Package Outline

The following figure shows the package outline drawing of the MSCSM120AM027T6AG device. The dimensions in the following figure are in millimeters.

#### Figure 2-1. Package Outline Drawing



Note: See APT0601—Mounting Instructions for SP6 Power Modules for more information.

## 3. Revision History

Revision	Date	Description
A	06/2022	Initial Revision.

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